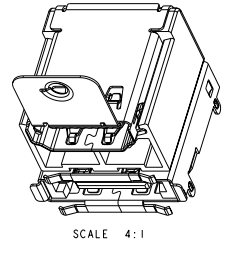
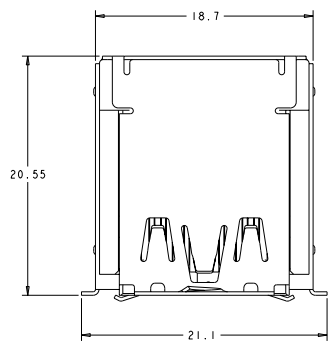
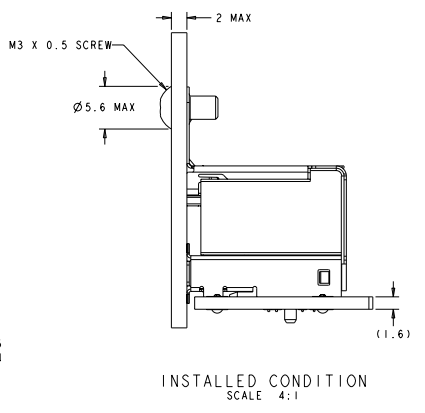
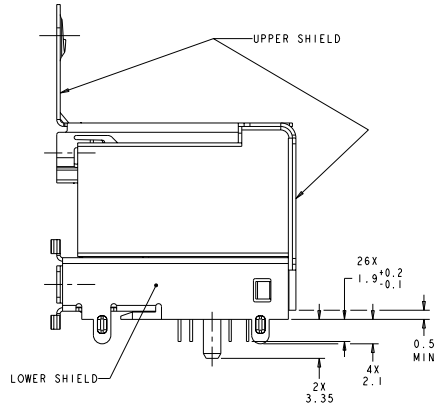
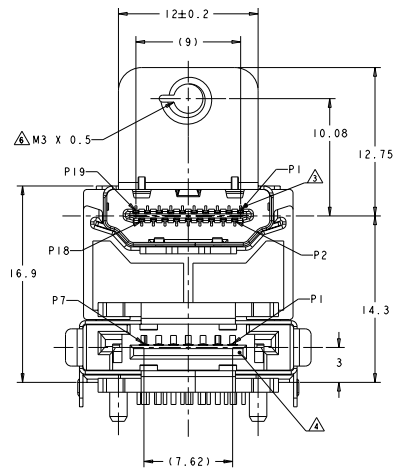


REV. NO.		DESCRIPTION	DATE	BY	CHK
00	F	REVISED PER ECO-08-030380			



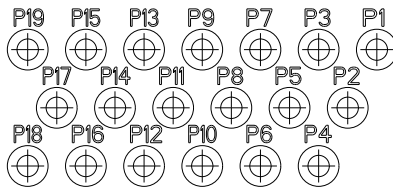
- △ MATERIALS:
 HOUSING: HIGH TEMP THERMOPLASTIC, UL94V-0, BLACK.
 CONTACTS: COPPER ALLOY
 SHIELDS: STAINLESS STEEL
- △ FINISH:
 CONTACTS:
 GOLD FLASH OVER
 PALLADIUM-NICKEL PLATE, 0.3µm MIN TOTAL ON THE MATING SURFACE,
 2µm MIN TIN PLATE ON THE SOLDER-TAIL,
 2µm MIN NICKEL UNDERPLATE ON THE ENTIRE CONTACT.
 OR
 0.3µm MIN GOLD PLATE ON THE MATING SURFACE,
 2µm MIN TIN PLATE ON THE SOLDER-TAIL,
 2µm MIN NICKEL UNDERPLATE ON THE ENTIRE CONTACT.
- LOWER SHIELD:
 0.75µm MIN TIN OVER
 0.8µm MIN NICKEL UNDERPLATE
- △ INTERFACE DIMENSIONS ARE PER HDMI SPECIFICATION VERSION 1.3a.
- △ INTERFACE DIMENSIONS ARE PER SERIAL ATA REVISION 2.5.
- 5. WAVE SOLDER COMPATIBLE PER 109-202, CONDITION B,
 NO CLEAN FLUX IS RECOMMENDED.
- △ APPLIED TORQUE MUST NOT EXCEED 4 kg-cm (3.47 in-lbs).



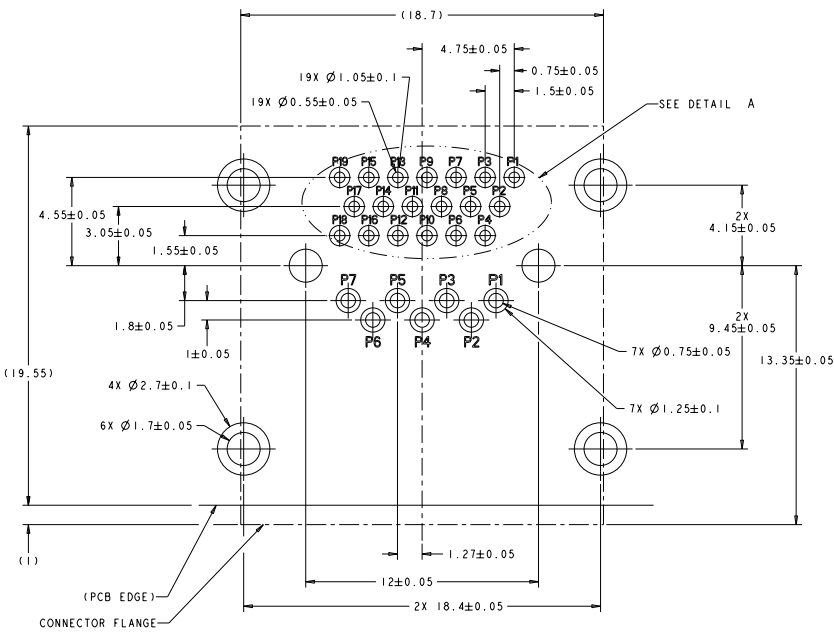
1888540-1
 PART NO

DATE: 29 JUN 2004	DESIGNED BY: T. J. MCELLELLAN	CHECKED BY: T. J. MCELLELLAN	APPROVED BY: T. J. MCELLELLAN
REVISED BY: T. J. MCELLELLAN	REVISED DATE: 29 JUN 2004	REVISED REASON: REVISED PER ECO-08-030380	REVISED BY: T. J. MCELLELLAN
DATE: 29 JUN 2004	DESIGNED BY: T. J. MCELLELLAN	CHECKED BY: T. J. MCELLELLAN	APPROVED BY: T. J. MCELLELLAN
DATE: 29 JUN 2004	DESIGNED BY: T. J. MCELLELLAN	CHECKED BY: T. J. MCELLELLAN	APPROVED BY: T. J. MCELLELLAN

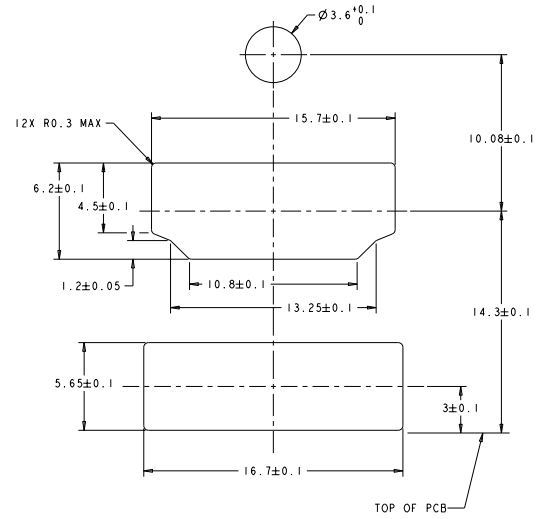
REV	DATE	DESCRIPTION	BY	CHK	APP
00		SEE SHEET 1			



DETAIL A
SCALE 20:1



PCB LAYOUT
SHOWN FROM CONNECTOR SIDE
TOLERANCES ARE NON-CUMULATIVE
SCALE 10:1



RECOMMENDED PANEL CUTOUT
SCALE 8:1

DATE: 29 JUN 2004 DRAWN BY: J. MCELLELLAN CHECKED BY: J. MCELLELLAN DATE: 29 JUN 2004 TITLE: HDMI/E-SATA STACKED CONNECTOR ASSEMBLY PART NO: 00779-1888540 CUSTOMER DRAWING: YES		Tech Electronics Harrisburg, PA 17105-3600 SCALE CODE: DRAWING NO. 00779-1888540 SHEET: 6 OF 2	
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